



PATENT
1794-0142P

IN THE U. S. PATENT AND TRADEMARK OFFICE

Applicants: Hideki HIRAYAMA et al. Conf: 8855
Serial No.: 09/943,222 Art Unit: 1765
Filed: August 31, 2001 Examiner: M.J. SONG
For: LOW DISLOCATION BUFFER AND PROCESS FOR PRODUCTION
THEREOF AS WELL AS DEVICE PROVIDED WITH LOW
DISLOCATION BUFFER

#10A
415703
mw

AMENDMENT UNDER 37 C.F.R. §1.111

Assistant Commissioner for Patents
Washington, DC 20231

RECEIVED

APR 14 2003

TC 1700
April 8, 2003

Sir:

In response to the Office Action mailed December 09, 2002 (Paper No. 8), the period of response having been extended one (1) month to April 9, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application:

IN THE CLAIMS:

Please rewrite claims 1-9 and 19-26 as follows:

1. (Amended) A buffer formed between a substrate and a nitride semiconductor as a device material to be formed for constituting a device structure on said substrate, comprising:

04/10/2003 CNGUYEN 00000111 09943222

01 FC:1202
02 FC:1251

18.00 OP
110.00 OP